

## CLAIMS

1. (Amended) A board for printed wiring made by treating the surface of a board whereon a conductor wiring is to be formed by one of the following surface treatment methods:

(1) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm;

(2) plasma treatment;

(3) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by plasma treatment, or

(4) surface roughening treatment for achieving center line average roughness Ra in a range from 30 to 300 nm followed by the step of forming a porous metal layer made of at least one kind of metal selected from among the group consisting of Al, Cr, Co, Ni, Cu and Ag, by sputtering.

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10. (Amended) A printed wiring board made by forming a conductor wiring by printing an electrically conductive paste containing metal particles M used as an electrically conductive filler and a binder B in volume ratio of  $M/B = 1/1$  to  $1.9/1$  on the surface of the board for printed wiring of claim 1 whereon the surface treatment has been applied, etching the surface of the conductor wiring on at least a portion thereof used for connection with an external circuit so as to expose the metal particles on the surface, and forming a plating layer by electroless plating on the surface of the conductor wiring where the metal particles have been exposed by etching.

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